



This Month at QP Technologies

Welcome to October – the month of falling leaves, cooler temperatures... and IMAPS 2021! We'll be onsite next week in San Diego at the [54th International Symposium on Microelectronics](#), October 12-14. We're proud to be a keynote sponsor at this year's event, which will include dynamic keynotes from executives with Intel, Samsung, Cadence, Xilinx and other industry leaders, as well as an evening keynote and panel session on October 13 moderated by Jan Vardaman of TechSearch International. If you'll be attending IMAPS 2021 in person, please come by our booth #109 to chat with our packaging experts about our solutions for wafer prep, packaging, assembly, and custom substrate development.



Feature of the Month: QP Tech Is Growing

Last month, we [announced](#) that QP Technologies is on a strong growth path, thanks to rising demand for our packaging and assembly knowhow. In fiscal 2020, we recorded double-digit growth over the prior year, and we have added people and equipment to ensure we stay on top of your needs. We've added equipment to our line, including state-of-the-art systems for Au, Al, ribbon and heavy wire bonding; we're seeing increased call for our custom substrate and interposer capabilities; and the onshoring trend is helping to drive concurrent demand for our stateside packaging and assembly capabilities in our ITAR-registered Escondido, Calif., facility. We've also expanded our team, filling new posts with seasoned executives including Darin Valley, director of quality assurance (profiled in our September newsletter), and Tom Bianchi, our new director of sales and marketing. For more about Tom, read on!

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Employee Spotlight: Tom Bianchi, Director of Sales & Marketing

Sustaining growth requires a strong, well-staffed sales organization. The latest addition to our sales team is Tom Bianchi, reporting to our VP of sales and marketing, Rosie Medina. Tom came on board in mid-September, bringing with him a wealth of industry experience in OSATs, semiconductors and electronics. He joined QP Tech from 3D Glass Solutions, where he served as VP of sales and marketing, and before that, he was VP of North American sales at Carsem Technology. Other prior roles include executive positions at Amkor Technology, Olin Corp., and Kyocera International, and he founded his own manufacturer representative firm AccuRep Technical Sales. A mover and shaker, Tom is excited to help take QP Technologies to the next level of success!





News Highlight: OCPP Explained

One of our core packaging offerings is our Open-cavity Plastic Package (OCP)[®] technology, which we featured in our August newsletter. We're experiencing some exciting successes with OCP, helping customers solve their need for cost-effective parts that fit their existing specs and footprint by reclaiming and repurposing existing IC plastic packages into open-cavity packages, ready to be assembled with new die. Our Sam Sadri, a senior packaging engineer, recently recorded a video interview with Ed Sperling, editor of *Semiconductor Engineering*, to explain how OCP works and why it's experiencing a surge in popularity.

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About QP Technologies

QP Technologies is a leading provider of microelectronic packaging and assembly, wafer preparation, and substrate design and development services. We leverage proven technologies developed by our skilled staff, and we work closely with you to get your products to market quickly, with the highest quality prototype and production volumes.

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